



## Materials Declaration Form

<b>IPC Form Type *</b>	<b>1752</b> Distribute	<b>Version</b>	<b>2</b>
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D <i>* : Required Field</i>

Supplier Information			
<b>Company Name *</b>	<b>STMicroelectronics</b>	<b>Response Date *</b>	<b>2014-09-25</b>
<b>Contact Name *</b>	Refer to "Supplier Comment" section	<b>Contact Title</b>	Refer to "Supplier Comment" section
<b>Contact Phone *</b>	Refer to "Supplier Comment" section	<b>Contact Email *</b>	Refer to "Supplier Comment" section
<b>Authorized Representative *</b>	Antonella Lanzafame	<b>Representative Title</b>	AMS & IPD Materials Declaration Champion
<b>Representative Phone *</b>	Refer to "Supplier Comment" section	<b>Representative Email *</b>	Refer to "Supplier Comment" section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/internet/com/support/online_tech_support.jsp">http://www.st.com/internet/com/support/online_tech_support.jsp</a>		

**Uncertainty Statement**

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**Legal Statement**

<b>Supplier Acceptance *</b>	<b>true</b>	<b>Legal Declaration *</b>	<b>Standard</b>
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**Legal Statement**

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	A1BB*AU04AAA	A	Z6GA	2014-09-25
Amount	UoM	Unit type	ST ECOPACK Grade	
73.00	mg	Each	ECOPACK® 2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
3	235	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable ; if coating is used o	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
QFN	4.0,4.0,1.8	24	flat	
Comment	QFN 4x4x1.8 24LD; MD valid for CP : AIS3624DQTR,AIS3624DQ.			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	true
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false
Exemption Id.	Description

QueryList : REACH-16th June 2014			
Query			Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH			true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application
			ppm in product

Material Composition Declaration						Mfr Item Name	A1BB*AU04AAA					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Silicon die	Other inorganic materials	8.976	mg	supplier	Silicon die	Silicon (Si)	7440-21-3		8.58	mg	955882	117534
Silicon die			mg	supplier	Alloy	Aluminium (Al)	7429-90-5		0.005	mg	557	68
Silicon die			mg	supplier	Alloy	Titanium Nitride (TiN)	25583-20-4		0.001	mg	111	14
Silicon die			mg	supplier	Alloy	Tungsten (W)	7440-33-7		0.001	mg	111	14
Silicon die			mg	Supplier	Wire	Silicon Nitride (SiN)	68034-42-4		0.01	mg	1114	137
Silicon die			mg	Supplier	Encapsulation	Silicon Oxide(SiO2)	7631-86-9		0.076	mg	8467	1041
Silicon die			mg	Supplier	Encapsulation	Lead Oxide (PbO)	proprietary		0.303	mg	33757	4151
Bonding wire	Bonding wire	0.127	mg	Supplier	Wire	Au	proprietary		0.127	mg	1000000	1740
Encapsulation	Other inorganic materials	46.752	mg	Supplier	Encapsulation	Silica Fused (75~95%)	proprietary		41.211	mg	881481	564534
Encapsulation			mg	Supplier	Encapsulation	Epoxy ResinA (1~5%)	proprietary		1.169	mg	25004	16014
Encapsulation			mg	Supplier	Encapsulation	Epoxy ResinB (1~5%)	proprietary		1.169	mg	25004	16014
Encapsulation			mg	Supplier	Encapsulation	Phenol ResinA (1~5%)	proprietary		1.169	mg	25004	16014
Encapsulation			mg	Supplier	Encapsulation	Phenol ResinB (1~5%)	proprietary		1.169	mg	25004	16014
Encapsulation			mg	Supplier	Encapsulation	Metal Hydroxide(0.5~2.5%)	proprietary		0.702	mg	15015	9616
Encapsulation			mg	Supplier	Encapsulation	Carbon Black (0.1~0.5%)	1333-86-4		0.163	mg	3486	2233
Leadframe	Copper and its alloy	16.264	mg	Supplier	Alloy	Cu	7440-50-8		15.637	mg	961449	214205
Leadframe			mg	Supplier	Alloy	Fe	7439-89-6		0.369	mg	22688	5055
Leadframe			mg	Supplier	Alloy	Iron Phosphide (Fe2P)	1310-43-6		0.005	mg	307	68
Leadframe			mg	Supplier	Alloy	Zn	1314-13-2		0.024	mg	1476	329
Leadframe			mg	Supplier	Plating	Ag	7440-22-4		0.229	mg	14080	3137
Die Attach 1	Other organic materials	0.204	mg	Supplier	Epoxy film	Polyethylene resin	proprietary		0.081	mg	663934	1110
Die Attach 1			mg	Supplier	Epoxy film	Soft PVC resin	proprietary		0.041	mg	336066	562
Die Attach 1			mg	Supplier	Epoxy film	Epoxy resin	proprietary		0.021	mg	256098	288
Die Attach 1			mg	Supplier	Epoxy film	Polyethylene terephthalate	proprietary		0.051	mg	621951	699
Die attach 2	Other organic materials	0.126	mg	Supplier	Epoxy	Polydimethylsiloxane with vinyl groups	proprietary		0.084	mg	666667	1151
Die attach 2			mg	Supplier	Epoxy	Fumed silica (SiO2)	14808-60-7		0.031	mg	246032	425
Die attach 2			mg	Supplier	Epoxy	Polydimethylsiloxane with hydrogen groups	68037-59-2		0.01	mg	79365	137
Die attach 2			mg	Supplier	Epoxy	platinum compound	proprietary		0.001	mg	7937	14
Finishing	Other inorganic materials	0.551	mg	Supplier	Connection coating	Tin	7440-31-5		0.551	mg	1000000	7548
			mg		Epoxy							